



US 20150340615A1

(19) **United States**(12) **Patent Application Publication**
KANG(10) **Pub. No.: US 2015/0340615 A1**(43) **Pub. Date: Nov. 26, 2015**(54) **DONOR MASK AND METHOD OF
MANUFACTURING ORGANIC LIGHT
EMITTING DISPLAY APPARATUS USING
THE SAME****H01L 51/52** (2006.01)**H01L 51/56** (2006.01)(52) **U.S. Cl.**CPC **H01L 51/0013** (2013.01); **H01L 51/56**
(2013.01); **H01L 27/3244** (2013.01); **H01L**
51/5271 (2013.01); **H01L 2227/323** (2013.01)(71) Applicant: **Samsung Display Co., Ltd.**, Yongin-city
(KR)(72) Inventor: **Tae-Wook KANG**, Yongin-city (KR)(21) Appl. No.: **14/504,892**(22) Filed: **Oct. 2, 2014**(30) **Foreign Application Priority Data**

May 23, 2014 (KR) 10-2014-0062590

Publication Classification(51) **Int. Cl.****H01L 51/00** (2006.01)**H01L 27/32** (2006.01)(57) **ABSTRACT**

A method of manufacturing an organic light emitting display apparatus using a donor mask. The donor mask includes a base substrate, a light to heat conversion layer provided on the base substrate, and a reflection layer disposed between the base substrate and the light to heat conversion layer and comprising a through hole corresponding to a first transfer region, a non-transfer region having a first thickness and a second transfer region having a second thickness smaller than the first thickness, and the organic light emitting display apparatus using the same.

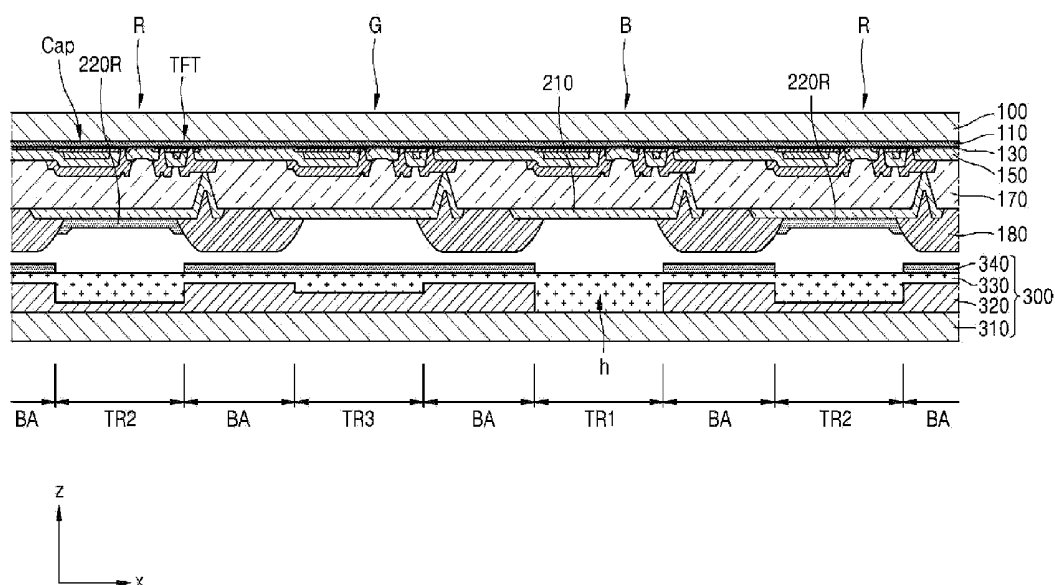


FIG. 1

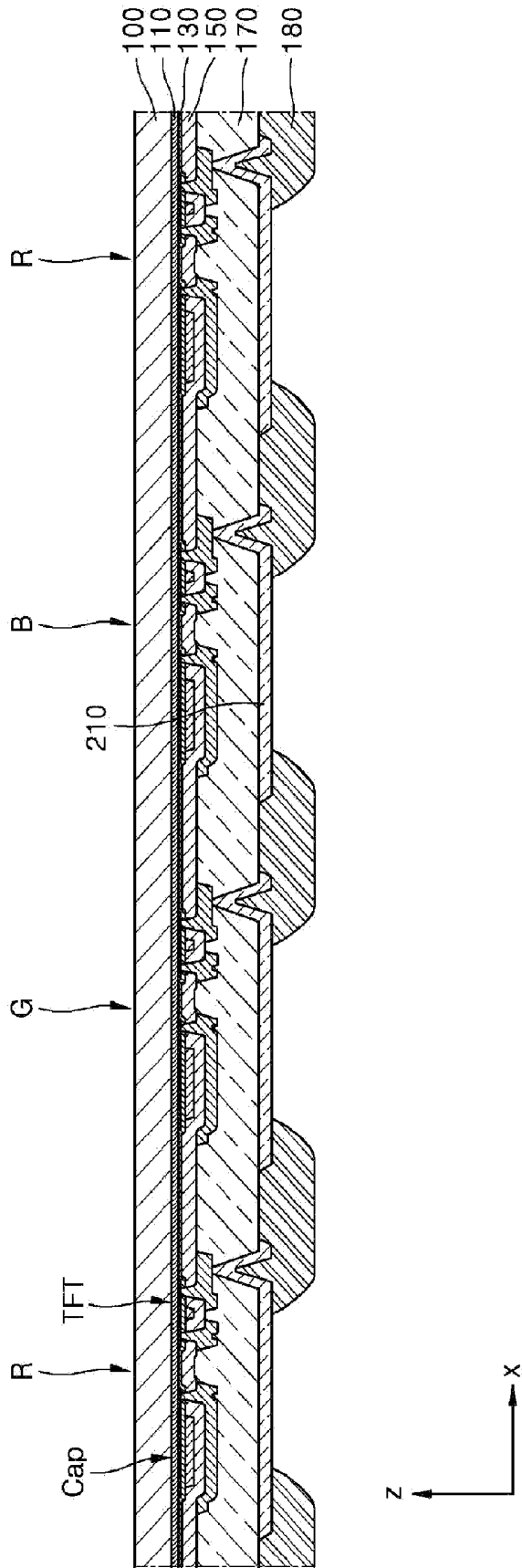


FIG. 2

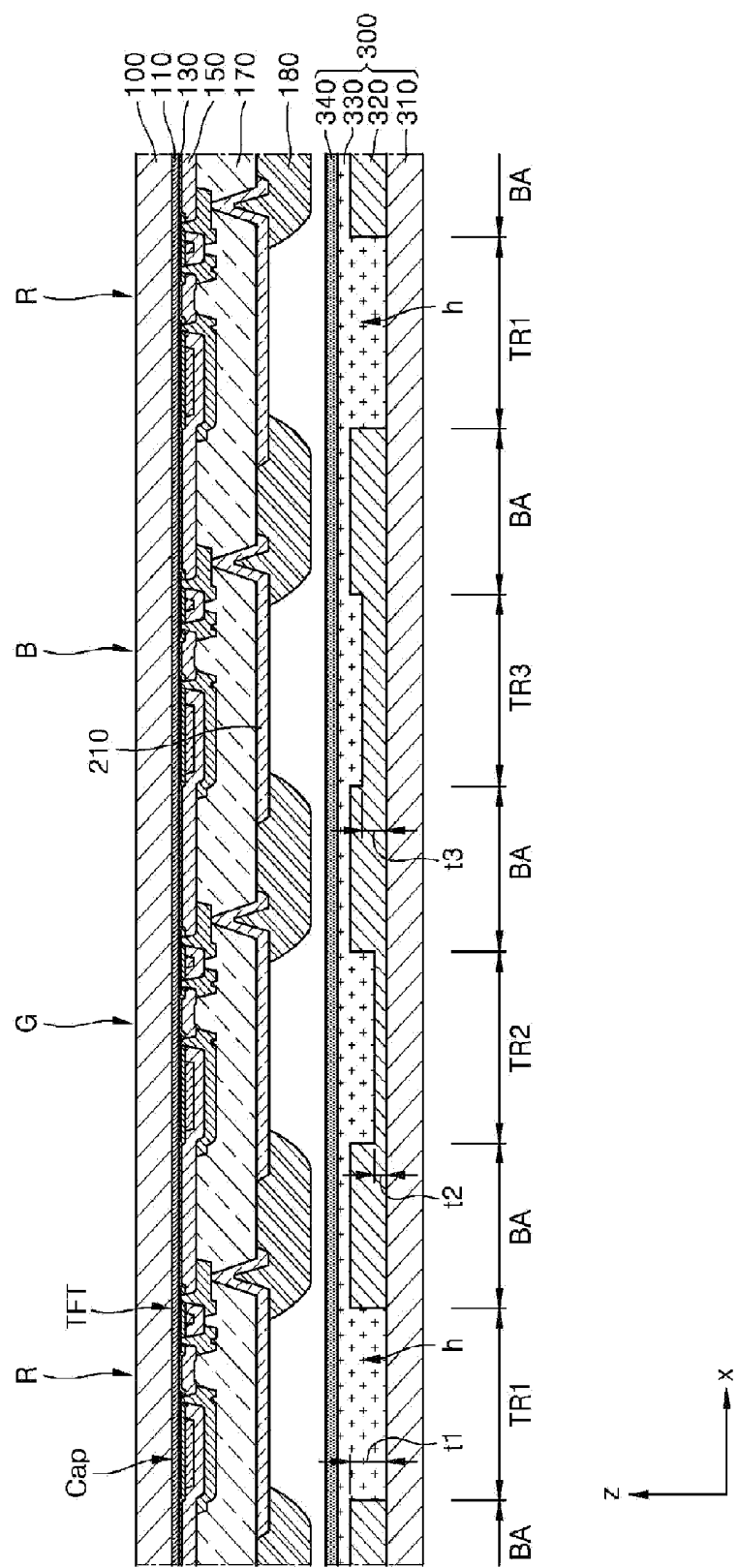


FIG. 3

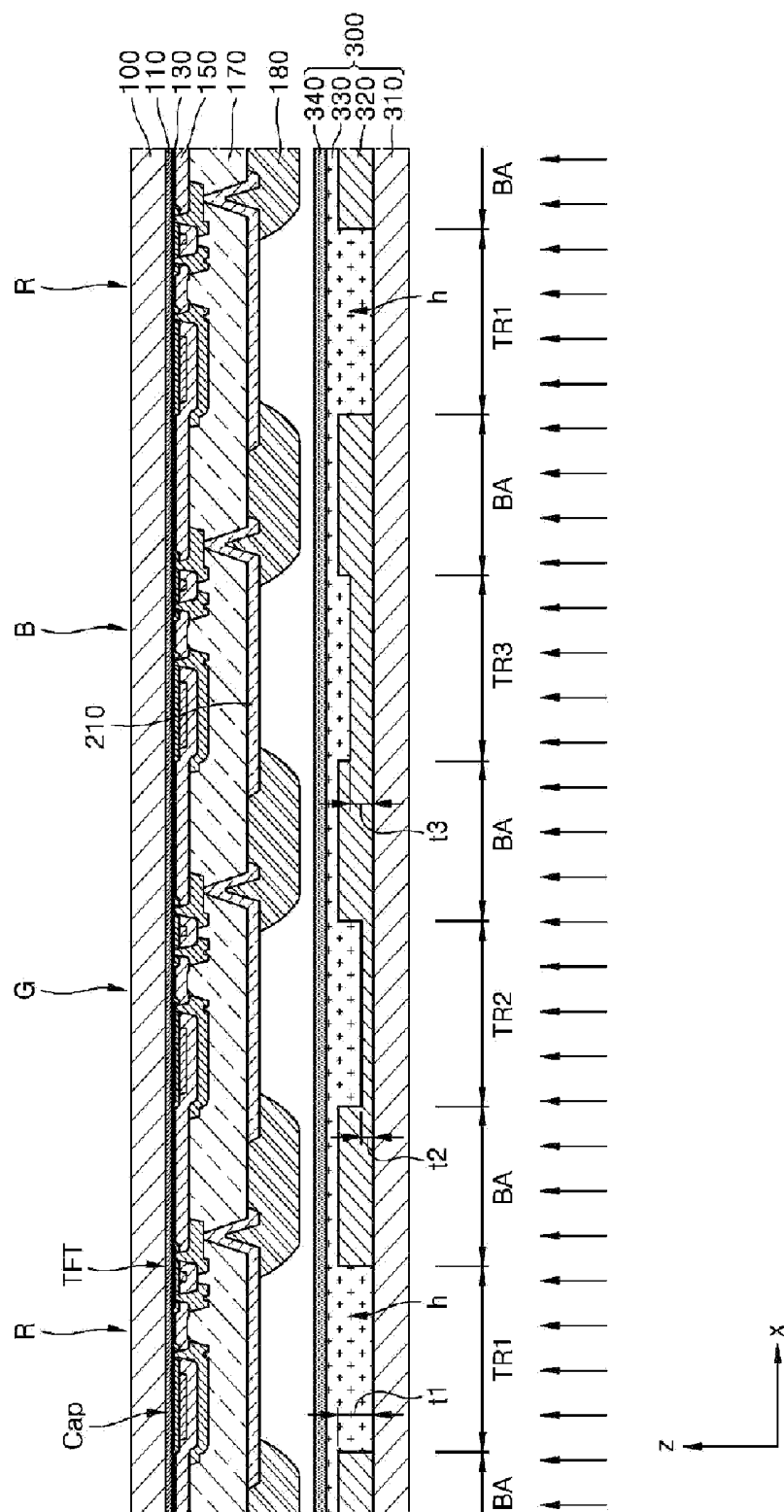


FIG. 5

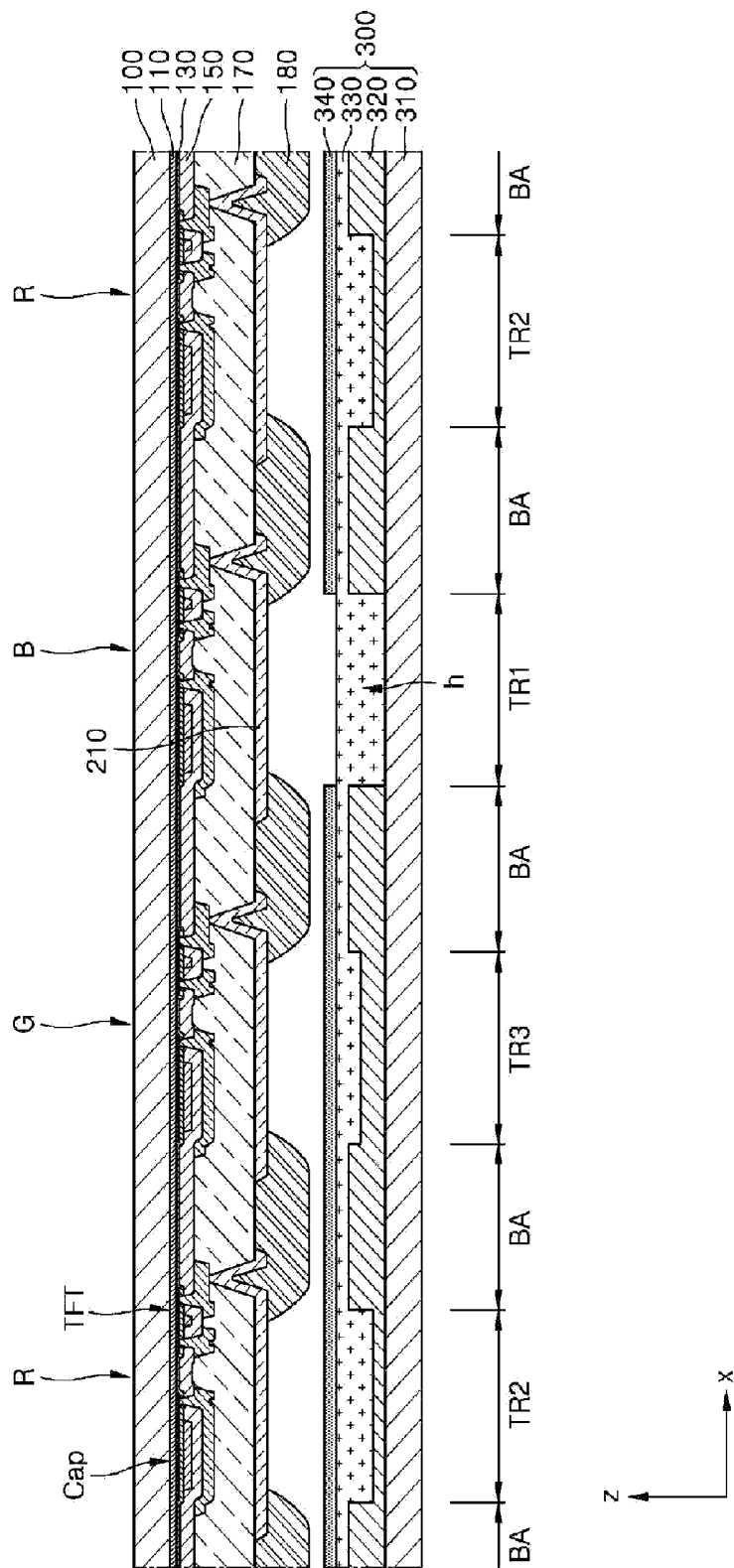


FIG. 8

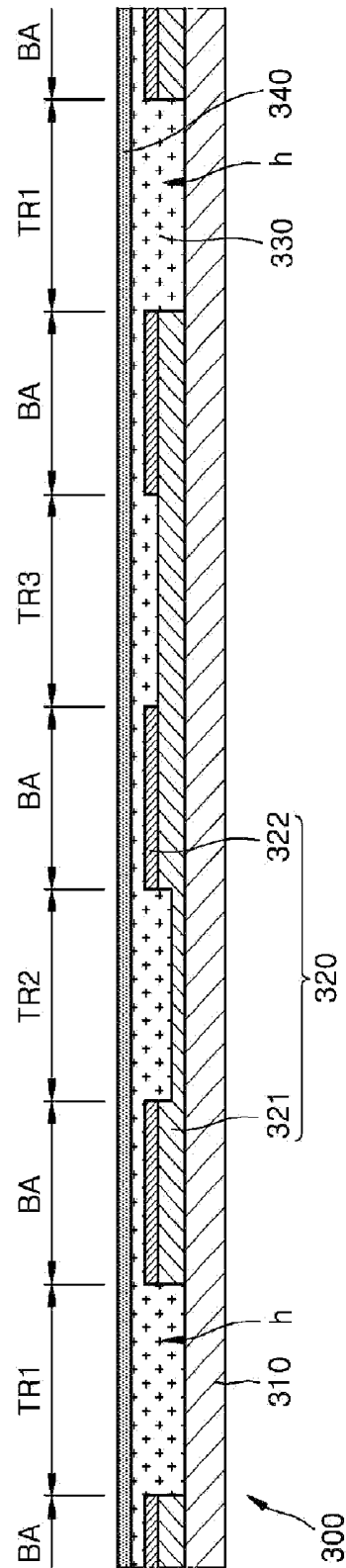


FIG. 9

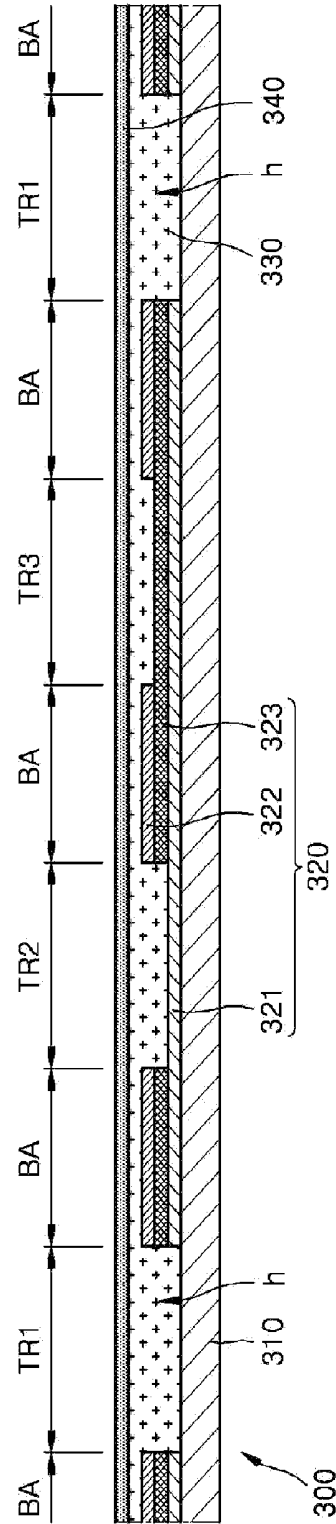
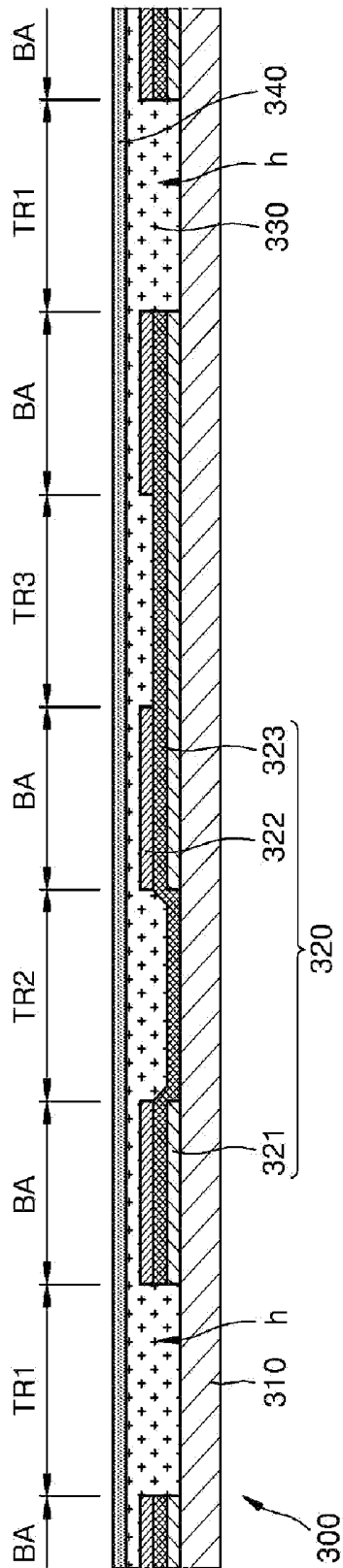


FIG. 10



**DONOR MASK AND METHOD OF
MANUFACTURING ORGANIC LIGHT
EMITTING DISPLAY APPARATUS USING
THE SAME**

CROSS-REFERENCE TO RELATED
APPLICATION

[0001] This application claims priority from and the benefit of Korean Patent Application No. 10-2014-0062590, filed on May 23, 2014, which is hereby incorporated by reference for all purposes as if fully set forth herein.

BACKGROUND

[0002] 1. Field

[0003] Exemplary embodiments relate to a donor mask and a method of manufacturing an organic light emitting display apparatus using the same, and more particularly, to a donor mask for dramatically increasing material usage efficiency and a method of manufacturing an organic light emitting display apparatus using the same.

[0004] 2. Discussion of the Background

[0005] An organic light emitting display apparatus is a display apparatus including an organic-light emitting diode (OLED) in a display region, wherein the OLED includes a pixel electrode and an opposing electrode that face each other, and an intermediate layer disposed between the pixel and opposing electrodes and including an emission layer.

[0006] Various methods may be used to form the emission layer when manufacturing the organic light-emitting display apparatus, such as a deposition method, an inkjet printing method, etc.

[0007] However, a general method of manufacturing an organic light-emitting display apparatus has problems, such as a complex process of forming the emission layer and an excessive amount of materials used to form the emission layer.

[0008] The above information disclosed in this Background section is only for enhancement of understanding of the background of the inventive concept, and, therefore, it may contain information that does not form the prior art that is already known in this country to a person of ordinary skill in the art.

SUMMARY

[0009] Exemplary embodiments provide a donor mask for dramatically increasing material usage efficiency and a method of manufacturing an organic light emitting display apparatus using the same.

[0010] Additional aspects will be set forth in the detailed description which follows, and, in part, will be apparent from the disclosure, or may be learned by practice of the inventive concept.

[0011] According to one or more embodiments of the present disclosure, a donor mask includes a base substrate, a light to heat conversion layer disposed on the base substrate; and a reflection layer disposed between the base substrate and the light to heat conversion layer and including a through hole, a non-transfer area having a first thickness, and a second transfer region having a second thickness smaller than the first thickness.

[0012] The donor mask may further include a transfer layer disposed on the light to heat conversion layer.

[0013] The donor mask may include a first alignment mark related to the through hole and a second alignment mark related to the second transfer region.

[0014] The greater a thickness of the reflection layer of the donor mask, the lower a light transmittance.

[0015] The reflection layer of the donor mask may include a third transfer region having a third thickness that is smaller than the first thickness and greater than the second thickness. The donor mask may include a first alignment mark related to the through hole, a second alignment mark related to the second transfer region, and a third alignment mark related to the third transfer region.

[0016] The reflection layer of the donor mask may have a single layer structure. The reflection layer of the donor mask may have a multilayer structure. The reflection layer of the donor mask may include a light block layer corresponding to the non-transfer region.

[0017] According to one or more embodiments of the present disclosure, a method of manufacturing an organic light-emitting display apparatus includes: preparing a first substrate on which a plurality of pixel electrodes are formed; preparing a second substrate on which a plurality of pixel electrodes are formed; preparing a donor mask including a base substrate, a light to heat conversion layer provided on the base substrate, and a reflection layer disposed between the base substrate and the light to heat conversion layer and including a through hole corresponding to a first transfer region, a non-transfer region having a first thickness, and a second transfer region having a second thickness smaller than the first thickness; depositing a transfer layer on the light to heat conversion layer of the donor mask; aligning the first substrate and the donor mask; transferring a part corresponding to the through hole of the transfer layer of the donor mask onto a part of the plurality of pixel electrodes on the first substrate; aligning of the first substrate and the donor mask; and transferring a part corresponding to the second transfer region of the transfer layer of the donor mask onto a part of the plurality of pixel electrodes on the second substrate.

[0018] The transfer layer may include an emission layer.

[0019] The donor mask may include a first alignment mark related to the through hole and a second alignment mark related to the second transfer region, wherein the aligning of the first substrate and the donor mask includes: using the first alignment mark of the donor mask, and wherein the aligning of the first substrate and the donor mask includes: using the second alignment mark of the donor mask.

[0020] The method may further include: re-depositing a transfer layer on the light to heat conversion layer of the donor mask.

[0021] The transferring of the part corresponding to the through hole and the transferring of the part corresponding to the second transfer region may include: irradiating a flash lamp or a laser beam onto the base substrate of the donor mask, and evaporating, vaporizing, or sublimating the part of the transfer layer where the flash lamp or laser beam is irradiated.

[0022] An intensity of the flash lamp or the laser beam in the transferring of the part corresponding to the second transfer region may be greater than that of the flash lamp or the laser beam in the transferring of the part corresponding to the through hole.

[0023] The foregoing general description and the following detailed description are exemplary and explanatory and are intended to provide further explanation of the claimed subject matter.

BRIEF DESCRIPTION OF THE DRAWINGS

[0024] The accompanying drawings, which are included to provide a further understanding of the inventive concept, and are incorporated in and constitute a part of this specification, illustrate exemplary embodiments of the inventive concept, and, together with the description, serve to explain principles of the inventive concept.

[0025] These and/or other aspects will become apparent and more readily appreciated from the following description of the embodiments, taken in conjunction with the accompanying drawings in which:

[0026] FIGS. 1 through 7 are schematic cross-sectional views for describing a method of manufacturing an organic light-emitting display apparatus, according to an embodiment of the present disclosure;

[0027] FIG. 8 is a schematic cross-sectional view of a donor mask according to an embodiment of the present disclosure;

[0028] FIG. 9 is a schematic cross-sectional view of a donor mask according to another embodiment of the present disclosure; and

[0029] FIG. 10 is a schematic cross-sectional view of a donor mask according to another embodiment of the present disclosure.

DETAILED DESCRIPTION OF THE ILLUSTRATED EMBODIMENTS

[0030] In the following description, for the purposes of explanation, numerous specific details are set forth in order to provide a thorough understanding of various exemplary embodiments. It is apparent, however, that various exemplary embodiments may be practiced without these specific details or with one or more equivalent arrangements. In other instances, well-known structures and devices are shown in block diagram form in order to avoid unnecessarily obscuring various exemplary embodiments.

[0031] In the accompanying figures, the size and relative sizes of layers, films, panels, regions, etc., may be exaggerated for clarity and descriptive purposes. Also, like reference numerals denote like elements.

[0032] When an element or layer is referred to as being “on,” “connected to,” or “coupled to” another element or layer, it may be directly on, connected to, or coupled to the other element or layer or intervening elements or layers may be present. When, however, an element or layer is referred to as being “directly on,” “directly connected to,” or “directly coupled to” another element or layer, there are no intervening elements or layers present. For the purposes of this disclosure, “at least one of X, Y, and Z” and “at least one selected from the group consisting of X, Y, and Z” may be construed as X only, Y only, Z only, or any combination of two or more of X, Y, and Z, such as, for instance, XYZ, XYY, YZ, and ZZ. Like numbers refer to like elements throughout. As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items.

[0033] Although the terms first, second, etc. may be used herein to describe various elements, components, regions, layers, and/or sections, these elements, components, regions, layers, and/or sections should not be limited by these terms.

These terms are used to distinguish one element, component, region, layer, and/or section from another element, component, region, layer, and/or section. Thus, a first element, component, region, layer, and/or section discussed below could be termed a second element, component, region, layer, and/or section without departing from the teachings of the present disclosure.

[0034] Spatially relative terms, such as “beneath,” “below,” “lower,” “above,” “upper,” and the like, may be used herein for descriptive purposes, and, thereby, to describe one element or feature’s relationship to another element(s) or feature(s) as illustrated in the drawings. Spatially relative terms are intended to encompass different orientations of an apparatus in use, operation, and/or manufacture in addition to the orientation depicted in the drawings. For example, if the apparatus in the drawings is turned over, elements described as “below” or “beneath” other elements or features would then be oriented “above” the other elements or features. Thus, the exemplary term “below” can encompass both an orientation of above and below. Furthermore, the apparatus may be otherwise oriented (e.g., rotated 90 degrees or at other orientations), and, as such, the spatially relative descriptors used herein interpreted accordingly.

[0035] The terminology used herein is for the purpose of describing particular embodiments and is not intended to be limiting. As used herein, the singular forms, “a,” “an,” and “the” are intended to include the plural forms as well, unless the context clearly indicates otherwise. Moreover, the terms “comprises,” “comprising,” “includes,” and/or “including,” when used in this specification, specify the presence of stated features, integers, steps, operations, elements, components, and/or groups thereof, but do not preclude the presence or addition of one or more other features, integers, steps, operations, elements, components, and/or groups thereof.

[0036] Various exemplary embodiments are described herein with reference to sectional illustrations that are schematic illustrations of idealized exemplary embodiments and/or intermediate structures. As such, variations from the shapes of the illustrations as a result, for example, of manufacturing techniques and/or tolerances, are to be expected. Thus, exemplary embodiments disclosed herein should not be construed as limited to the particular illustrated shapes of regions, but are to include deviations in shapes that result from, for instance, manufacturing. For example, an implanted region illustrated as a rectangle will, typically, have rounded or curved features and/or a gradient of implant concentration at its edges rather than a binary change from implanted to non-implanted region. Likewise, a buried region formed by implantation may result in some implantation in the region between the buried region and the surface through which the implantation takes place. Thus, the regions illustrated in the drawings are schematic in nature and their shapes are not intended to illustrate the actual shape of a region of a device and are not intended to be limiting.

[0037] Unless otherwise defined, all terms (including technical and scientific terms) used herein have the same meaning as commonly understood by one of ordinary skill in the art to which this disclosure is a part. Terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the relevant art and will not be interpreted in an idealized or overly formal sense, unless expressly so defined herein.

[0038] FIGS. 1 through 7 are schematic cross-sectional views for describing a method of manufacturing an organic

light-emitting display apparatus, according to an embodiment of the present disclosure.

[0039] First, as shown in FIG. 1, a backplane is prepared. The backplane may at least include a first substrate 100, a pixel electrode 210 formed on the substrate 100, and a pixel-defining film 180 exposing at least a part of the pixel electrode 210 including a center portion thereof. The pixel-defining film 180 may protrude farther than the pixel electrode 210 with respect to the first substrate 100.

[0040] The pixel electrode 210 may be a (semi-)transparent electrode or a reflective electrode. When the pixel electrode 210 is the (semi-)transparent electrode, the pixel electrode 210 may be formed of indium tin oxide (ITO), indium zinc oxide (IZO), zinc oxide (ZnO), indium oxide (In_2O_3), indium gallium oxide (IGO), or aluminum zinc oxide (AZO). When the pixel electrode 210 is the reflective electrode, the pixel electrode 210 may include a reflective film formed of silver (Ag), magnesium (Mg), aluminum (Al), platinum (Pt), palladium (Pd), gold (Au), nickel (Ni), neodymium (Nd), iridium (Ir), chromium (Cr), or a compound thereof, and a film formed of ITO, IZO, ZnO, or In_2O_3 . However, structures and materials of the pixel electrode 210 are not limited thereto and may vary.

[0041] The pixel-defining film 180 may include an opening corresponding to each subpixel, i.e., an opening exposing the center portion of the pixel electrode 210 or the entire pixel electrode 210 to define a pixel. Also, the pixel-defining film 180 may increase a distance between an end of the pixel electrode 210 and an opposing electrode (not shown) at a top portion of the pixel electrode 210 to prevent an arc from being generated at the end of the pixel electrode 210.

[0042] The backplane may further include other components if required. For example, as shown in FIG. 1, a thin-film transistor TFT or a capacitor Cap may be formed on the first substrate 100. Also, the backplane may further include other components, such as a buffer layer 110 preventing impurities from penetrating into a semiconductor layer of the thin-film transistor TFT, a gate insulation film 130 insulating the semiconductor layer of the thin-film transistor TFT and a gate electrode, an interlayer insulation film 150 for insulating source and drain electrodes of the thin-film transistor TFT and the gate electrode, and a planarization film 170 covering the thin-film transistor TFT and having an approximately flat top surface.

[0043] After preparing the backplane as described above, a donor mask 300 is provided to face the pixel electrode 210 and the pixel defining film 180 of the backplane as shown in FIG. 2. In more detail, as shown in FIGS. 1 and 2, the pixel electrode 210 and the pixel defining film 180 of the backplane are provided to face downward ($-z$ direction), and the donor mask 300 is provided in a lower portion of the backplane. Before placing the backplane and the donor mask 300, a layer such as a hole injection layer or a hole transport layer may be previously formed on the pixel electrode 210 or on an entire surface of the first substrate 100.

[0044] The donor mask 300 may include a base substrate 310, a reflection layer 320, a light to heat conversion layer 330, and a transfer layer 340. In this regard, the transfer layer 340 is not a component of the donor mask 300 but may be merely formed on the donor mask 300. That is, a process of preparing the donor mask 300 and depositing the transfer layer 340 on the donor mask 300 may be used to manufacture the organic light-emitting display apparatus.

[0045] The base substrate 310 is configured to form a general outer shape of the donor mask 300, and may be formed of glass to transmit light to the light to heat conversion layer 330. Alternatively, the base substrate 310 may be formed of polyester such as polyethylene terephthalate (PET), polyacryl, polyepoxy, polyethylene and/or polystyrene.

[0046] The light to heat conversion layer 330 is a layer for absorbing flash lamp light or a laser beam when irradiated and converting at least a part of the energy of the absorbed flash lamp light or laser beam to heat. The light to heat conversion layer 330 may be a metal film formed of a metal such as aluminum or silver capable of absorbing light in an infrared light-visible light region, an oxide/sulfide film of such a metal, or an organic polymer film including carbon black or graphite.

[0047] The reflection layer 320 is disposed between the base substrate 310 and the light to heat conversion layer 330. The reflection layer 320 includes a through hole h, a non-transfer area BA having a first thickness t1, and a second transfer region TR2 having a second thickness t2 smaller than the first thickness t1. In this regard, the through hole h may be a first transfer region TR1 in the donor mask 300. As shown in FIG. 2, the reflection layer 320 may include a third transfer region TR3 having a third thickness t3 smaller than the first thickness t1 and greater than the second thickness t2.

[0048] The reflection layer 320 may be formed by using a halftone mask or forming a layer having a uniform thickness and removing a part of the layer on the base substrate 310. The reflection layer 320 may be formed of Ti, Al, Cu, Ag, Mo, an alloy of these, CrN, TiAlCu, etc. Alternatively, the reflection layer 320 may be formed of TiOx, SiOx, SiCN, etc.

[0049] The transfer layer 340 is a layer that may be evaporated, vaporized, or sublimated by heat generated in the light to heat conversion layer 330, and may, for example, include a luminous material. The transfer layer 340 may be a layer including a hole injection material, a layer including a hole transport material, a layer including an electron transport material, or a layer including an electron injection material if necessary.

[0050] When the backplane and the donor mask 300 are provided as shown in FIG. 2, it is necessary to exactly align the backplane and the donor mask 300. That is, it is necessary to exactly align the backplane and the donor mask 300 in order to enable the first transfer region TR1 of the donor mask 300 to correspond to a preset part of the backplane.

[0051] The transfer layer 340 of the donor mask 300 includes a luminous material that may emit red light in FIG. 2, and thus the backplane and the donor mask 300 are aligned so as to enable the through hole h of the reflection layer 320 that is the first transfer region TR1 of the donor mask 300 to correspond to the pixel electrode 210 of a red subpixel R. To this end, the backplane and the donor mask 300 may be configured to have an alignment key and a first alignment mark related to the through hole h. Accordingly, when the alignment key of the backplane and the first alignment mark of the donor mask 300 have a preset reciprocal location relationship, the through hole h of the reflection layer 320 that is the first transfer region TR1 of the donor mask 300 may correspond to the pixel electrode 210 of the red subpixel R.

[0052] Thereafter, as shown in FIG. 3, lamp light or the laser beam (schematically indicated by the arrows) is irradiated onto the donor mask 300 at a preset first intensity or lower by using a flash lamp or a laser beam generator so that a part of the transfer layer 340 of the donor mask 300 is

transferred to the backplane. In this regard, although the lamp light or the laser beam is irradiated onto the entire surface of the donor mask **300** by using the flash lamp or the laser beam generator, the lamp light or the laser beam is blocked by the reflection layer **320** for the most part and reaches the light to heat conversion layer **330** only in the first transfer region **TR1** corresponding to the through hole **h** of the reflection layer **320**. Accordingly, only the first transfer region **TR1** in the transfer layer **340** of the donor mask **300** is evaporated, vaporized, or sublimated, and thus a red emission layer **220R** is formed only in the pixel electrode **210** of the red subpixel **R** as shown in FIG. 4.

[0053] After the red emission layer **220R** is formed as described above, the donor mask **300** may be exchanged to form a green emission layer or a blue emission layer on the pixel electrode **210** of a green subpixel **G** or a red subpixel **B**. If necessary, an electron injection layer, an electron transport layer, etc. are formed, and opposing electrodes corresponding to the red subpixel **R**, the green subpixel **G**, and the blue subpixel **B** are formed, thereby manufacturing the organic light-emitting display apparatus.

[0054] Meanwhile, as shown in FIG. 4, after the red emission layer **220R** is formed, the donor mask **300** may be used to manufacture another organic light-emitting display apparatus. That is, as shown in FIG. 5, the donor mask **300** may be aligned in a new backplane (for forming the red emission layer **220R**). The new backplane may be a second substrate on which a plurality of the pixel electrodes **210** is formed. In this regard, the transfer layer **340** is not present in the first transfer region **TR1** of the donor mask **300**, and thus it is necessary to align the new backplane and the donor mask **300** so as to enable the second transfer region **TR2** of the donor mask **300** to correspond to a preset part of the new backplane.

[0055] The transfer layer **340** of the donor mask **300** includes the luminous material that may emit red light in FIG. 5, and thus the new backplane and the donor mask **300** are aligned so as to enable the second transfer region **TR2** that is a part of the second thickness **t2** of the reflection layer **320** of the donor mask **300** to correspond to the pixel electrode **210** of the red subpixel **R**. To this end, the donor mask **300** may be configured to have a second alignment mark related to the second transfer region **TR2** that is a part of the second thickness **t2** of the reflection layer **320**, in addition to the first alignment key related to the through hole **h** as described above. Accordingly, when the alignment key of the new backplane (i.e., the second substrate) and the second alignment mark of the donor mask **300** have a preset reciprocal location relationship, the second transfer region **TR2** that is the part of the second thickness **t2** of the reflection layer **320** of the donor mask **300** may correspond to the pixel electrode **210** of the red subpixel **R**.

[0056] Thereafter, as shown in FIG. 6, the lamp light or the laser beam (indicated schematically by the arrows) is irradiated onto the donor mask **300** at a second intensity that is higher than the preset first intensity or lower than a preset third intensity by using the flash lamp or the laser beam generator so that a part of the transfer layer **340** of the donor mask **300** is transferred to the new backplane.

[0057] That is, if the lamp light or the laser beam is irradiated at an intensity lower than the preset first intensity, the lamp light or the laser beam may pass through only the through hole **h** of the reflection layer **320** and may mostly not pass through the reflection layer **320** itself. In this regard, if the lamp light or the laser beam is irradiated at the second

intensity that is higher than the preset first intensity and lower than the preset third intensity, the lamp light or the laser beam may pass through the through hole **h** of the reflection layer **320** and a part of the reflection layer **320** having the smallest thickness (a thinnest part of the reflection layer **320**), i.e. the second transfer region **TR2** having the second thickness **t2**, and reach the light to heat conversion layer **330**. Since the lamp light or the laser beam is irradiated at an intensity lower than the preset third intensity, the lamp light or the laser beam mostly does not pass through the reflection layer **320** other than the through hole **h** of the reflection layer **320** or the second transfer region **TR2**.

[0058] As described above, if the lamp light or the laser beam is irradiated at the second intensity that is higher than the preset first intensity or is lower than the preset third intensity, heat is generated in the light to heat conversion layer **330** so that a part of the transfer layer **340** corresponding to the second transfer region **TR2** is evaporated, vaporized, or sublimated, and thus the red emission layer **220R** is formed only in the pixel electrode **210** of the red subpixel **R** as shown in FIG. 7. Although the lamp light or the laser beam reaches the light to heat conversion layer **330** in the first transfer region **TR1** of the donor mask **300**, since the transfer layer **340** is not present in the first transfer region **TR1**, the red emission layer is not formed in the pixel electrode **210** of the blue subpixel **B**.

[0059] Meanwhile, as shown in FIG. 7, the donor mask **300** may be used to manufacture another organic light-emitting display apparatus.

[0060] That is, the donor mask **300** may be configured to have a third alignment mark related to the third transfer region **TR3** that is the part of the reflection layer **320** having the third thickness **t3**, in addition to the first alignment key related to the through hole **h** or the second alignment mark related to the second transfer region **TR2** that is the part of the reflection layer **320** having the second thickness **t2** as described above. Accordingly, when an alignment key of a new backplane (i.e., a third substrate) and the third alignment mark of the donor mask **300** have a preset reciprocal location relationship, the part of the third thickness **t3** of the reflection layer **320** that is the third transfer region **TR3** of the donor mask **300** may correspond to the pixel electrode **210** of the red subpixel **R**.

[0061] Thereafter, the lamp light or the laser beam is irradiated onto the donor mask **300** at the preset third intensity or higher by using the flash lamp or the laser beam generator so that a part of the transfer layer **340** of the donor mask **300** is transferred to a new backplane.

[0062] That is, if the lamp light or the laser beam is irradiated at an intensity lower than the preset first intensity, the lamp light or the laser beam may pass through only the through hole **h** of the reflection layer **320** and may mostly not pass through the reflection layer **320** itself. If the lamp light or the laser beam is irradiated at the second intensity that is higher than the preset first intensity and lower than the preset third intensity, the lamp light or the laser beam may pass through the through hole **h** of the reflection layer **320** and the part of the reflection layer **320** having the smallest thickness (the thinnest part of the reflection layer **320**), i.e. the second transfer region **TR2** having the second thickness **t2**, and reach the light to heat conversion layer **330**. The lamp light or the laser beam mostly does not pass through the reflection layer **320** in a part of the reflection layer **320** having the first thickness **t1** that is greater than the third thickness **t3**.

[0063] As described above, if the lamp light or the laser beam is irradiated at the preset third intensity or higher, heat is generated in the light to heat conversion layer 330 so that a part of the transfer layer 340 corresponding to the third transfer region TR3 is evaporated, vaporized, or sublimated, and thus the red emission layer 220R is formed only in the pixel electrode 210 of the red subpixel R. Although the lamp light or the laser beam reaches the light to heat conversion layer 330 in the first transfer region TR1 or the second transfer region TR2 of the donor mask 300, since the transfer layer 340 is not present in the first transfer region TR1 or the second transfer region TR2, the red emission layer is not formed in the pixel electrode 210 of the blue subpixel B.

[0064] As described above, the method of manufacturing the organic light-emitting display apparatus of the present embodiment may dramatically increase material use efficiency. For example, if the reflection layer 320 includes a through hole while having a uniform thickness, after the red emission layer 220R is formed by transferring the transfer layer 340 on the pixel electrode 210 of the red subpixel R once as shown in FIG. 4, reuse is impossible, for example, a remaining part of the transfer layer 340 is discarded. However, according to the method of manufacturing the organic light-emitting display apparatus of the present embodiment, the reflection layer 320 includes parts having the first thickness t_1 through third thickness t_3 in addition to the through hole h , and thus the transfer layer 340 may be transferred to at least three backplanes. Thus, a part of the transfer layer 340 that is not transferred but remains is a part on the block area BA (the non-transfer area BA), thereby dramatically increasing the material use efficiency.

[0065] Meanwhile, a process of transferring the transfer layer 340 many times and then re-depositing the transfer layer 340 on the light to heat conversion layer 330 of the donor mask 300 may be used to form the red emission layer 220R on the pixel electrode 210 of the red subpixel R that is part of a new backplane.

[0066] The method of manufacturing the organic light-emitting display apparatus has been described hereinabove, but the present disclosure is not limited thereto. The donor mask 300 used in the method is also within the scope of the present disclosure.

[0067] The donor mask 300 according to an embodiment of the present disclosure may include the base substrate 310, the reflection layer 320, and the light to heat conversion layer 330 as shown in FIG. 2. The transfer layer 340 may be formed on the light to heat conversion layer 330 by using deposition.

[0068] The base substrate 310 is configured to form a general outer shape of the donor mask 300, and may be formed of glass to transmit light to the light to heat conversion layer 330. According to circumstances, the base substrate 310 may be formed of polyester such as PET, polyacryl, polyepoxy, polyethylene and/or polystyrene.

[0069] The light to heat conversion layer 330 is a layer for absorbing flash lamp light or a laser beam when irradiated and converting at least a part of energy of the absorbed flash lamp light or laser beam to heat. The light to heat conversion layer 330 may be a metal film formed of a metal such as aluminum or silver capable of absorbing light in an infrared light-visible light region, an oxide/sulfide film of such a metal, or an organic polymer film including carbon black or graphite.

[0070] The reflection layer 320 includes the through hole h , the non-transfer area BA having the first thickness t_1 , and the second transfer region TR2 having the second thickness t_2

smaller than the first thickness t_1 . In this regard, the through hole h may be the first transfer region TR1 in the donor mask 300. As shown in FIG. 2, the reflection layer 320 may include the third transfer region TR3 having a third thickness t_3 smaller than the first thickness t_1 and greater than the second thickness t_2 .

[0071] The greater the thickness of the reflection layer 320, the lower the light transmittance. Accordingly, if lamp light or a laser beam is irradiated onto the donor mask 300 at a preset first intensity or lower by using a flash lamp or a laser beam generator, the lamp light or the laser beam is mostly blocked by the reflection layer 320 and reaches the light to heat conversion layer 330 only in the first transfer region TR1 corresponding to the through hole h of the reflection layer 320. If the lamp light or the laser beam is irradiated at a second intensity that is higher than the preset first intensity and lower than preset third intensity, the lamp light or the laser beam may pass through the through hole h of the reflection layer 320 and a part of the reflection layer 320 having the smallest thickness (a thinnest part of the reflection layer 320), i.e. the second transfer region TR2 having the second thickness t_2 , and reach the light to heat conversion layer 330. Since the lamp light or the laser beam is irradiated at an intensity lower than the preset third intensity, the lamp light or the laser beam mostly does not pass through the reflection layer 320 other than the through hole h of the reflection layer 320 or the second transfer region TR2. Furthermore, if the lamp light or the laser beam is irradiated onto the donor mask 300 at the preset third intensity or higher, the lamp light or the laser beam mostly does not pass through the reflection layer 320 in the block area BA (the non-transfer area BA) that is a part of the reflection layer 320 having the first thickness t_1 that is greater than the third thickness t_3 .

[0072] The above-described donor mask 300 may include a first alignment mark related to the through hole h , a second alignment mark related to the second transfer region TR2, and a third alignment mark related to the third transfer region TR3.

[0073] Meanwhile, the reflection layer 30 may have a single layer structure as shown in FIG. 2 but the present disclosure is not limited thereto. That is, the reflection layer 320 may have a multilayer structure according to necessity.

[0074] For example, as shown in FIG. 8 that is a schematic cross-sectional view of the donor mask 300 according to an embodiment of the present disclosure, the reflection layer 320 may include a light blocking layer 322 corresponding to the non-transfer area BA. A semi-transmittance layer 321 that is a remaining part of the reflection layer 320 may include the through hole h , the second transfer region TR2 having the second thickness t_2 , and the third transfer region TR3 having the third thickness t_3 . The semi-transmittance layer 321 is also present in the non-transfer area BA and thus may be present in a lower portion of the light blocking layer 322. When the transfer layer 340 of the first transfer region TR1, the second transfer region TR2, and/or the third transfer region TR3 is transferred, the light blocking layer 322 may originally block lamp light or a laser beam from reaching the light to heat conversion layer 330 in the non-transfer area BA. The light blocking layer 322 may include metal having excellent light blocking performance or a black matrix material.

[0075] FIG. 9 is a schematic cross-sectional view of the donor mask 300 according to another embodiment of the present disclosure. In the donor mask 300 according to the present embodiment, the reflection layer 320 has a multilayer

structure including a first semi-transmittance layer **321** and a second semi-transmittance layer **323** in addition to the light blocking layer **322**. Accordingly, a part of the donor mask **300** in which both the first semi-transmittance layer **321** and the second semi-transmittance layer **323** include the through hole **h** is the through hole **h** of the reflection layer **320** that forms the first transfer region **TR1**, a part of the donor mask **300** only including the first semi-transmittance layer **321** forms the second transfer region **TR2**, a part of the donor mask **300** in which both the first semi-transmittance layer **321** and the second semi-transmittance layer **323** are present as a layered structure forms the third transfer layer **TR3**, and a part of the donor mask **300** in which the first semi-transmittance layer **321**, the second semi-transmittance layer **323**, and the light block layer **322** are present forms the non-transfer area **BA**.

[0076] An area of the first semi-transmittance layer **321** is greater than that of the second semi-transmittance layer **323** in FIG. 9 but the present disclosure is not limited thereto. For example, as shown in FIG. 10, the area of the second semi-transmittance layer **323** is greater than that of the first semi-transmittance layer **321** so that a part of the second semi-transmittance layer **323** may directly contact the base substrate **310**. In this case, the part of the donor mask **300** in which both the first semi-transmittance layer **321** and the second semi-transmittance layer **323** include the through hole **h** is the through hole **h** of the reflection layer **320** and forms the first transfer region **TR1**, the part of the donor mask **300** only including the first semi-transmittance layer **321** forms the second transfer region **TR2**, the part of the donor mask **300** in which the first semi-transmittance layer **321** and the second semi-transmittance layer **323** are present as the layered structure forms the third transfer layer **TR3**, and the part of the reflection layer **320** in which the first semi-transmittance layer **321**, the second semi-transmittance layer **323**, and the light blocking layer **322** are present forms the non-transfer area **BA**.

[0077] The reflection layer **320** may have a different structure, for example, a multilayer structure of a metal layer and an inorganic layer or a multilayer structure of only the inorganic layer.

[0078] The method of manufacturing the organic light-emitting display apparatus described above may also use the donor mask **300** as shown in one of FIGS. 8 through 10 or the modified donor mask **300**.

[0079] As described above, according to the one or more of the above embodiments of the present disclosure, a donor mask for dramatically increasing material use efficiency and a method of manufacturing an organic light emitting display apparatus using the same may be implemented. However, the scope of the present disclosure is not limited by such an effect.

[0080] It should be understood that the exemplary embodiments described herein should be considered in a descriptive sense only and not for purposes of limitation. Descriptions of features or aspects within each embodiment should typically be considered as available for other similar features or aspects in other embodiments.

[0081] Although certain exemplary embodiments and implementations have been described herein, other embodiments and modifications will be apparent from this description. Accordingly, the inventive concept is not limited to such embodiments, but rather to the broader scope of the presented claims and various obvious modifications and equivalent arrangements.

What is claimed is:

1. A method of manufacturing an organic light-emitting display apparatus, the method comprising:
 - preparing a first substrate comprising a plurality of pixel electrodes;
 - preparing a second substrate comprising a plurality of pixel electrodes;
 - preparing a donor mask comprising a base substrate, a light to heat conversion layer disposed on the base substrate, a reflection layer disposed between the base substrate and the light to heat conversion layer and comprising a through hole corresponding to a first transfer region, a non-transfer region having a first reflection layer thickness, and a second transfer region having a second reflection layer thickness smaller than the first thickness;
 - depositing a transfer layer on the light to heat conversion layer of the donor mask;
 - aligning the first substrate and the donor mask;
 - transferring a portion of the transfer layer corresponding to the through hole of the reflection layer of the donor mask onto a part of the plurality of pixel electrodes on the first substrate;
 - aligning the second substrate and the donor mask; and
 - transferring a portion of the transfer layer corresponding to the second transfer region of the transfer layer of the donor mask onto a part of the plurality of pixel electrodes on the second substrate.
2. The method of claim 1, wherein the transfer layer comprises an emission layer.
3. The method of claim 1, wherein the donor mask comprises a first alignment mark related to the through hole and a second alignment mark related to the second transfer region, wherein the aligning of the first substrate and the donor mask comprises: using the first alignment mark of the donor mask, and wherein the aligning of the first substrate and the donor mask comprises: using the second alignment mark of the donor mask.
4. The method of claim 1, further comprising: re-depositing a transfer layer on the light to heat conversion layer of the donor mask.
5. The method of claim 1, wherein the transferring of the portion of the transfer layer corresponding to the through hole and the transferring of the portion of the transfer layer corresponding to the second transfer region comprise: irradiating a flash lamp or a laser beam onto the base substrate of the donor mask, and evaporating, vaporizing, or sublimating a part of the transfer layer where the flash lamp or laser beam is irradiated.
6. The method of claim 5, wherein an intensity of the flash lamp or the laser beam in the transferring of the portion of the transfer layer corresponding to the second transfer region is greater than that of the flash lamp or the laser beam in the transferring of the portion of the transfer layer corresponding to the through hole.
7. The method of claim 1, wherein the greater a thickness of the reflection layer of the donor mask, the lower a light transmittance.
8. The method of claim 1, wherein the reflection layer of the donor mask comprises a third transfer region having a third thickness that is smaller than the first thickness and greater than the second thickness.
9. The method of claim 8, wherein the donor mask comprises a first alignment mark related to the through hole, a

second alignment mark related to the second transfer region, and a third alignment mark related to the third transfer region, wherein the aligning of the first substrate and the donor mask comprises: using the first alignment mark of the donor mask, and wherein the aligning of the first substrate and the donor mask comprises: using the second alignment mark of the donor mask, further comprising: aligning a third substrate and the donor mask by using the third alignment mark; and transferring a portion of the transfer layer corresponding to the third transfer region of the transfer layer of the donor mask onto a part of a plurality of pixel electrodes on the third substrate.

10. The method of claim **1**, wherein the reflection layer of the donor mask has a single layer structure.

11. The method of claim **1**, wherein the reflection layer of the donor mask has a multilayer structure.

12. The method of claim **11**, wherein the reflection layer of the donor mask comprises a light blocking layer corresponding to the non-transfer region.

13. An organic light-emitting display apparatus formed by the process of claim **1**.

* * * * *

专利名称(译)	供体掩模和使用其制造有机发光显示装置的方法		
公开(公告)号	US20150340615A1	公开(公告)日	2015-11-26
申请号	US14/504892	申请日	2014-10-02
[标]申请(专利权)人(译)	三星显示有限公司		
申请(专利权)人(译)	三星DISPLAY CO. , LTD.		
当前申请(专利权)人(译)	三星DISPLAY CO. , LTD.		
[标]发明人	KANG TAE WOOK		
发明人	KANG, TAE-WOOK		
IPC分类号	H01L51/00 H01L27/32 H01L51/52 H01L51/56		
CPC分类号	H01L51/0013 H01L51/56 H01L2227/323 H01L51/5271 H01L27/3244 B41M5/382 H01L27/3211 H01L2251/558 Y02E10/549 Y02P70/521		
优先权	1020140062590 2014-05-23 KR		
其他公开文献	US9337428		
外部链接	Espacenet USPTO		

摘要(译)

一种使用施主掩模制造有机发光显示装置的方法。供体掩模包括基础基板，设置在基础基板上的光热转换层，以及设置在基础基板和光热转换层之间并包括对应于第一转移区域的通孔的反射层，非 - 具有第一厚度的转移区域和具有小于第一厚度的第二厚度的第二转移区域，以及使用该转移区域的有机发光显示装置。

